



Material Content Data Sheet



Sales Product Name		BFP 620 H7764		Issued		29. August 2013		
MA#		MA000808554						
Package		PG-SOT343-4-2		Weight*		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		421	
	non noble metal	tin	7440-31-5	0.001	0.01		109	
	inorganic material	silicon	7440-21-3	0.017	0.24	0.29	2449	2979
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.56	49.77	495597	497688
wire	noble metal	gold	7440-57-5	0.010	0.14	0.14	1427	1427
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4379	
	plastics	epoxy resin	-	0.652	9.42		94154	
	inorganic material	silicondioxide	60676-86-0	2.351	33.94	43.80	339393	437927
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28760	28761
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31220	31220
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com